

Specification Sheet

Model No. : HP7240-01-TSWG16P042-A

Description : 0.42" OLED Module 72 x 40 Pixel, SSD1306,4-Wire Serial,I2C, White Color

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STANDARD DOC.	PRODUCT SPEC.	MODULE NO.	HP7240-01-TSWG16P042-A	PAGE	2 / 26	
			<u>CONTENTS</u>			
1	CONTENTS			2		
2	RECORDS	OF REVISION		3		
3	GENERAL S	PECIFICATION	s	4		
4	FEATURES			4		
5	MACHANIC	AL SPECIFICAT	IONS	4		
6	OUTLINE D	IMENSIONS		5		
7	INERFACE	INERFACE SPECIFICATIONS				
8		ABSOLUTE MAXIMUM RATINGS				
9		ELECTRICAL CHARACTERISTICS				
10						
11		RELIABILITY Outgoing Quality Control Specifications				
12	Package Sp			19-22 		
14			ese OEL Display Modules	24-26		
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STANDARD DOC.	PRODUCT SPEC.	MODULE NO.	HP7240-01-7	HP7240-01-TSWG16P042-A		PAGE	3 / 2
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DATE	REVISED NO.	REVISE	D DESCRIPTIONS	PREPARED	CHECKE	D APPF	ROVED
10.16.201	7 VER1.0	FIRST ISSUE					

3. GENERAL SPECIFICATIONS :

3-1 SCOPE:

This specification covers the delivery requirements for the organic light emitting diode display delivered by quality to Customer.

3-2 PRODUCTS:

Organic light emitting diode (OLED)

3-3 MODULE NAME:

HP7240-01-TSWG16P042-A

NO.

4. FEATURES :

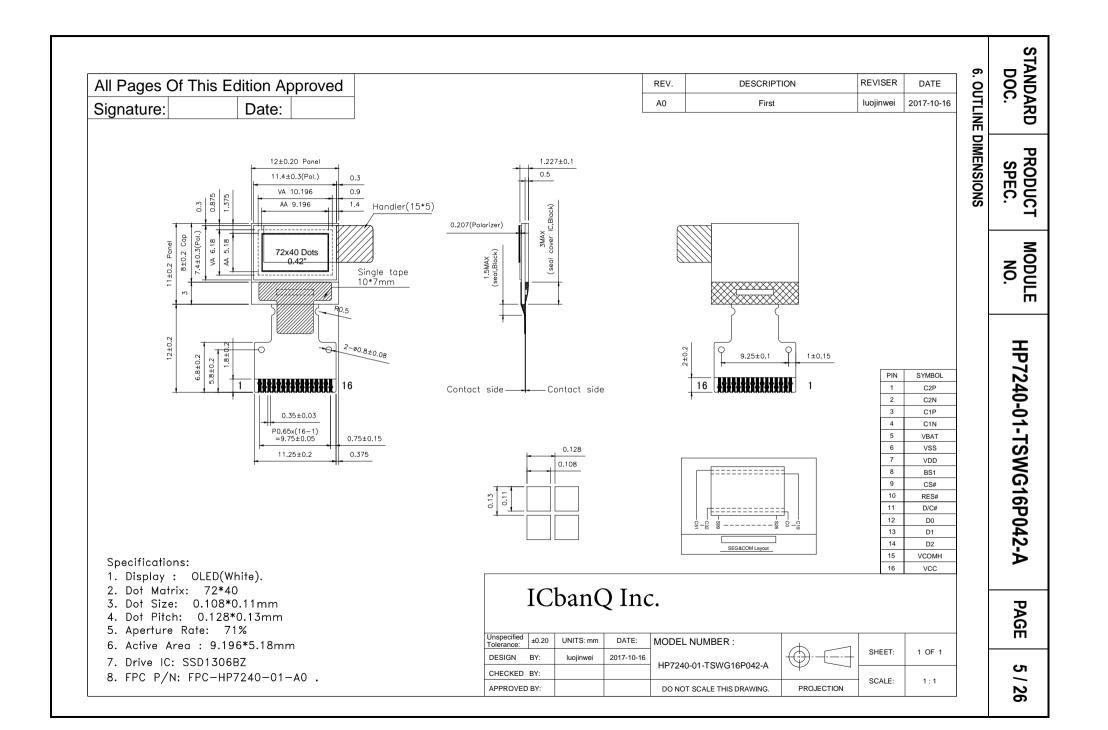
- (1) Display Color: WHITE
- (2) Dot Matrix: 72x40
- (3) Drive IC: SSD1306BZ
- (4) Viewing Angle: 160°
- (5) Aperture rate: 71%
- 4-WIRE Serial interface, I²C (6) Interface:

5. MACHANICAL SPECIFICATIONS :

ITEM	SPECIFICATIONS UNIT	
MODULE SIZE	12.0(W)x11.0(H)x1.227(D)	mm
VIEWING AREA	10.196 (W) x 6.18(H)	mm
ACTIVE AREA	9.196 (W) x5.18 (H)	mm
DOT SIZE	0.108(W) x0.11(H)	mm
DOT PITCH	0.128(W) x0.13 (H)	mm
ASSY.TYPE	COG	
WEIGHT	TBD	

NOTES:

OLED should be grounded during handling OLED.



ST	ANDARD DOC.	PRODU SPEC	-	MODULE HP7240-01-TSWG16P042-A		PAGE	6 / 26				
	7. INERFAC	CE SPECIFIC	ATIONS								
	7-1. PIN	ASSIGNM	IENT								
	PIN NO.	SYMBOL	TYPE			FUN	CTION DESCRIPT	IONS			
	1	C2P		C1P/C1N-P	in for chai	rge pur	np capacitor.				
	2	C2N		C2P/C2N-P	in for chai	rge pur	np capacitor.				
	3	C1P	'	Connect to	each othe	r with a	capacitor. They r	must be float	ted when tl	he	
	4	C1N		Charge pur	np not use).					
				Power supp	bly for chai	rge pur	np regulator circui	t.			
	5	VBAT	Р	lt must be c	connected	to exte	rnal source when	charge pum	p is used.		
				lt must be fl	loat when	charge	pump is not used				
	6	VSS	Р	Ground pin.	. It must be	e conne	ected to external g	ground.			
	7	VDD	Р	Power pin fo	or logic cir	cuit. It	must be connecte	d to externa	l source.		
				Interface se	election pir	ns.					
	8	BS1	Ι		I ² C	4SPI					
				BS1	1	0					
	9	CS#	I	Chip Select	input pin.	Active	"L"				
	10	RES#	I	Hardware re	eset input	pin. Ac	tive "L".				
				This is Data	a/Comman	d conti	ol pin.				
				When the p	in is pulled	d HIGH	, the data at D[7:0)] is data.			
	11	D/C#	I	When the p	in is pulled	d LOW	the data at D[7:0] is comma	and.		
				In I2C mode	e, this pin	acts as	SA0 for slave ad	dress section	n.		
				When 3-wire	e serial int	erface	is selected, this p	in must be c	onnected t	o VSS	
	12	D0		When seria	l interface	mode	is selected, D2 sl	hould be kep	ot NC, D1	will be	
	13	D1	I/O				D0 will be the seria	•			
14 D2 When I2C mode is selected, D2, D1 should be tied toge						ether and	serve				
		DL		as SDA and D0 is the serial clock input, SCL.							
	15	VCOMH	0	-	COM signal deselected voltage level.						
							ected between th				
					•		ing voltage. A ca		Ild be coni	nected	
	16	VCC	P	P between this pin and VSS, when charge pump is used.							
				It must be c	connected	to exte	rnal source when	charge pum	p is not us	ed.	

TANDARD DOC.	PRODUCT SPEC.	MODULE NO.	HP7240-()1-TSV	VG16P042-A	PAGE	7 / 26
	ICATION CIRC -Wire Serial Int		ernal Charge P	ımp			
(When d	esign main board	l, Please add Elec	tronic Switch circu	t, otherwi	se, will be caused leak o	current)	
			4SPI INTERFAC	E			
			SYMBOL	PIN			
- Vin	$\land \land \land R2$		C2P	1			
			C2N	2			
	G G G G	Q1	C1P	3			
			C1N	4			
GPIO	R3	- <u>C3</u>	VBAT	5			
VSS	<u> </u>	♦♦	VSS	6			
VDD	·	C4	VDD	7			
			BS1	8			
CS#			CS#	9			
RES#			RES#	10			
D/C#			D/C#	11			
SCLK			D0	12			
SDIN	·		D1	13			
		×		14			
			VCOMH	15			
VSS		• 08	VCC	16			
Pecomme	ended Compone	nte:					
C1, C2:	1µF / 16V, X						
C3, C4:	1µF / 16V, X						
C5,C6:	4.7µF / 25V						
R2, R3:	4.7μ1 723V 47kΩ						
R2, R3. Q1:							
	FDN338P						
Q2:	FDN335N						
Notes:	4.05 0.01/1	abaula ba anu 11					
VDD:		snould be equal t	o MPU I/O voltage				
Vin:	3.5~4.2V						

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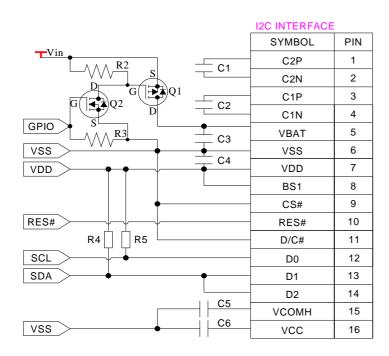
HP7240-01-TSWG16P042-A

7-2-2 I²C Interface With Internal Charge Pump

MODULE

NO.

(When design main board, Please add Electronic Switch circuit, otherwise, will be caused leak current)



Recommended Components:

C1, C2:	1µF / 16V, X5R
C3, C4:	1µF / 16V, X5R
C5,C6:	4.7µF / 25V
R2, R3:	47kΩ
R4, R5:	4.7kΩ
~	FRUGGOR

Q1: FDN338P

Q2: FDN335N

Notes:

VDD: 1.65~3.3V, it should be equal to MPU I/O voltage.

Vin: 3.5~4.2V

The I²C slave address is 0111100b

STANDARD DOC.

HP7240-01-TSWG16P042-A

8. ABSOLUTE MAXIMUM RATING

Characteristic	Symbol	S	Standard Value			Notes	
Gildidelensue	Symbol	MIN	TYP	MAX	Unit	Notes	
Power Supply Voltage(1)	V _{DD}	-0.3	-	+4.0	V	1,2	
Power Supply Voltage(2)	V _{BAT}	-0.3	-	4.5	V	1,2	
Power Supply Voltage(3)	V _{CC}	0	-	15.0	V	1,2	
Operating Temperature	T _{OPR}	-40	-	+70	ΟO		
Storage Temperature	T _{STG}	-40	-	+85	ΟO	3	
Life Time (120 cd/m ²)		10000	-	-	hour	4	
Life Time (80 cd/m ²)		30000	-	-	hour	4	
Life Time (60 cd/m ²)		50000	-	-	hour	4	

Note 1: All the above voltages are on the basis of " $V_{SS} = 0V$ ".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 9-1 "DC ELECTRICAL CHARACTERISTICS". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

Note 3: The defined temperature ranges do not include the polarizer. The maximum withstood temperature of the polarizer should be 80°C.

Note 4: V_{CC} =7.5V, T_a = 25°C, 50% Checkerboard.

End of lifetime is specified as 50% of initial brightness reached. The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

STANDARD DOC.

HP7240-01-TSWG16P042-A

9.ELECTRICAL CHARACTERISTICS

9-1 DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test condition	St	Unit		
Symbol	Faranielei	Test condition	MIN	TYP	MAX	Unit
V _{DD}	Logic Supply Voltage	-	1.65	2.8	3.3	V
V _{BAT}	Charge Pump Regulator Supply Voltage	Internal Charge Pump Enable	3.5	-	4.2	V
V _{CC}	Operating Voltage for OLED (Generated by charge pump)	Internal Charge Pump Enable	7.0	7.5		V
Vcc	Operating Voltage for OLED (Supplied Externally)	Internal Charge Pump Disable	8.5	9.0	9.5	V
ViH	High Logic Input Level		0.8*V _{DD}	-	-	V
VIL	Low Logic Input Level		-	-	0.2*V _{DD}	V
V _{OH}	High Logic Output Level	Ι _{ΟUT} = 100μΑ, 3.3MHz	0.9*V _{DD}	-	-	V
V _{OL}	Low Logic Output Level	Ι _{ουτ} = 100μΑ, 3.3MHz	-	-	0.1*V _{DD}	V
I _{DD, SLEEP}	IDD, Sleep Mode Current		-	-	10	uA
IBAT, SLEEP	IBAT, Sleep Mode Current		-	-	10	uA
I _{CC, SLEEP}	I _{CC,} Sleep Mode Current		-	-	10	uA
I _{DD}	V _{DD} Supply Current		-	50	150	uA
Icc	V _{CC} Supply Current (V _{CC} Supplied Externally)	V_{DD} = 2.8V, V_{CC} = 9V, 100% Display Area Turn on	-	5	10	mA
I _{BAT}	I _{BAT} Supply Current (V _{CC} Generated by charge pump)	V _{DD} = 2.8V, V _{CC} = 7.5V, 100% Display Area Turn on	-	22	25	mA

9-2 ELECTRO-OPTICAL CHARACTERISTICS

Symbol	Parameter	condition	St	Unit		
Symbol	Falametei	condition	MIN	TYP	MAX	Unit
L _{br}	Brightness (V _{CC} Supplied Externally)		360	-	-	cd/m ²
L _{br}	Brightness $(V_{CC}$ Generated by charge pump)		360	430	-	cd/m ²
(x)	C.I.E. (White)	C.I.E. 1931	0.25	0.29	0.33	
(y)	C.I.E. (White)	C.I.E. 1951	0.27	0.31	0.35	
CR	Dark Room Contrast		-	2000:1	-	
	Viewing Angle		-	160	-	degree

* Optical measurement taken at V_{DD} = 2.8V, V_{CC} = 9V & 7.5V.

STANDARD
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HP7240-01-TSWG16P042-A

9-3 AC ELECTRICAL CHARACTERISTICS

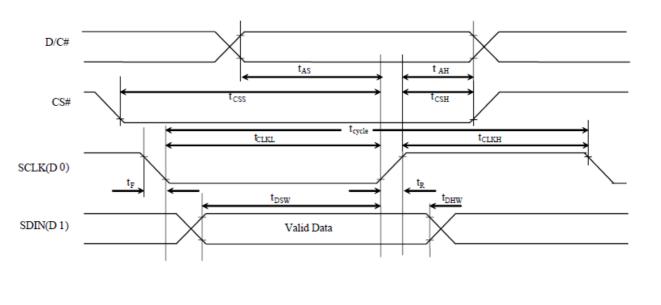
9-3-1 4 Wire Serial Interface Timing Characteristics

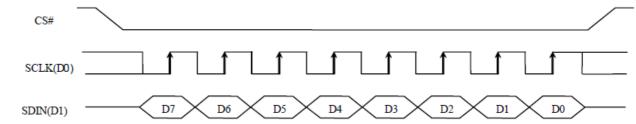
MODULE

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$(V_{DD} - V_{SS} = 1.65V \text{ to } 3.3V, T_A = 25^{\circ}C)$

Symbol	Parameter	Min	Тур	Max	Unit
t _{cycle}	Clock Cycle Time	100	-	-	ns
t _{AS}	Address Setup Time	15	-	-	ns
t _{AH}	Address Hold Time	15	-	-	ns
t _{CSS}	Chip Select Setup Time	20	-	-	ns
t _{CSH}	Chip Select Hold Time	10	-	-	ns
t _{DSW}	Write Data Setup Time	15	-	-	ns
t _{DHW}	Write Data Hold Time	15	-	-	ns
t _{CLKL}	Clock Low Time	20	-	-	ns
t _{CLKH}	Clock High Time	20	-	-	ns
t _R	Rise Time	-	-	40	ns
t _F	Fall Time	-	-	40	ns





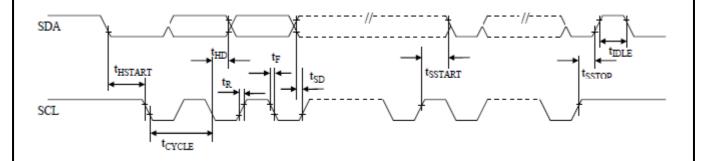
STANDARD	
DOC.	

PRODUCT SPEC.

MODULE NO.

HP7240-01-TSWG16P042-A

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9-3-2	I ² C Interface 7	I ² C Interface Timing Characteristics					
Symbol	Parameter			Min	Тур	Max	Unit
t _{cycle}	Clock Cycle T	lime		2.5	-	-	us
t _{HSTART}	Start condition	Start condition Hold Time			-	-	us
t _{HD}	Data Hold Time (for "SDA _{OUT} " pin)			0	-	-	ns
	Data Hold Time (for "SDA _{IN} " pin)			300	-	-	ns
t _{SD}	Data Setup Ti	Data Setup Time			-	-	ns
t _{sstart}		Start condition Setup Time (Only relevant for a repeated Start condition)			-	-	us
t _{sstop}	Stop condition	1 Setup Time		0.6	-	-	us
t _R	Rise Time for	Rise Time for data and clock pin			-	300	ns
t _F	Fall Time for	Fall Time for data and clock pin			-	300	ns
t _{IDLE}	Idle Time befo	ore a new trans	mission can start	1.3	-	-	us



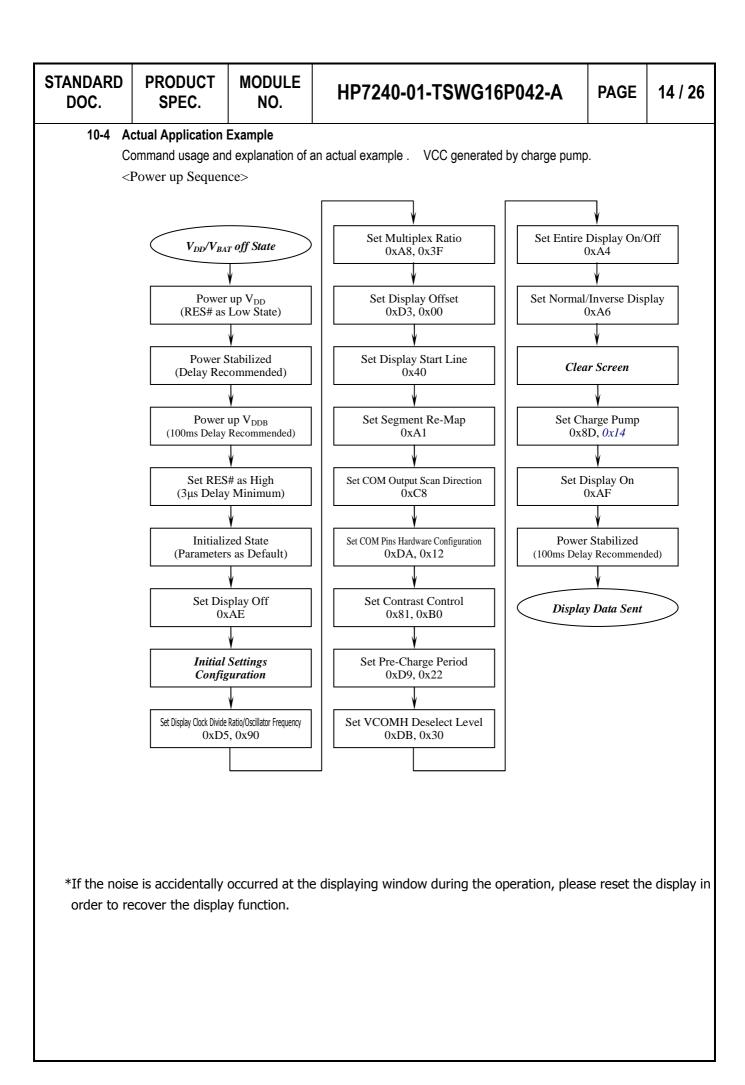
STANDARD DOC.	PRODUCT SPEC.	MODULE NO.	HP7240-01-TSWG16P042	-A	PAGE	13 / 26
10. FUNCT	IONNAL SPECI	FICATIONS				
10-1 CO	MMANDS					
	the SSD1306 IC					
10-2 PO	WER UP AND P	OWER DOWN SE	QUENCE			
•	•	•	el life time, the driver IC power up/down routir			• •
	• •	• •	power sources during turn on/off. It gives t	the OEL	panel enc	ough time
complet	e the action of cl	harge and discharg	ge before/after the operation.			
10-2-1	Power up Seq	uence:				
	1. Power up	V _{DD} / V _{BAT}		V	D. ON	
	2. Send Disp	lay off command		* 24	V _{CC} /VBAT	on
	3. Initializatio	n				Display on
	4. Clear Scre	en	v_{cc} –	· — · — ·		
	5. Power up					
	6. Delay 100		V _{-DD}			
	(When V _{cc}		V _{SS} /Ground		1	
	7. Send Disp	lay on command				
10-2-2	Power down S	equence:		_ 1	Display off	
	1. Send Disp	lay off command			V _{CC} / V _{BA}	
	2. Power dov	vn V _{CC} / V _{BAT}				V _{:DD} . off
	3. Delay 100	ms	V_{CC}/V_{BAT}			
	(When V _{cc}	$_{\rm s}$ / V _{BAT} is reach 0 a	and panel is completely discharges) $_{ m V_{DD}}$ -			
	4. Power dov	vn V _{DD}	V _{ss} /Ground			
Note:						

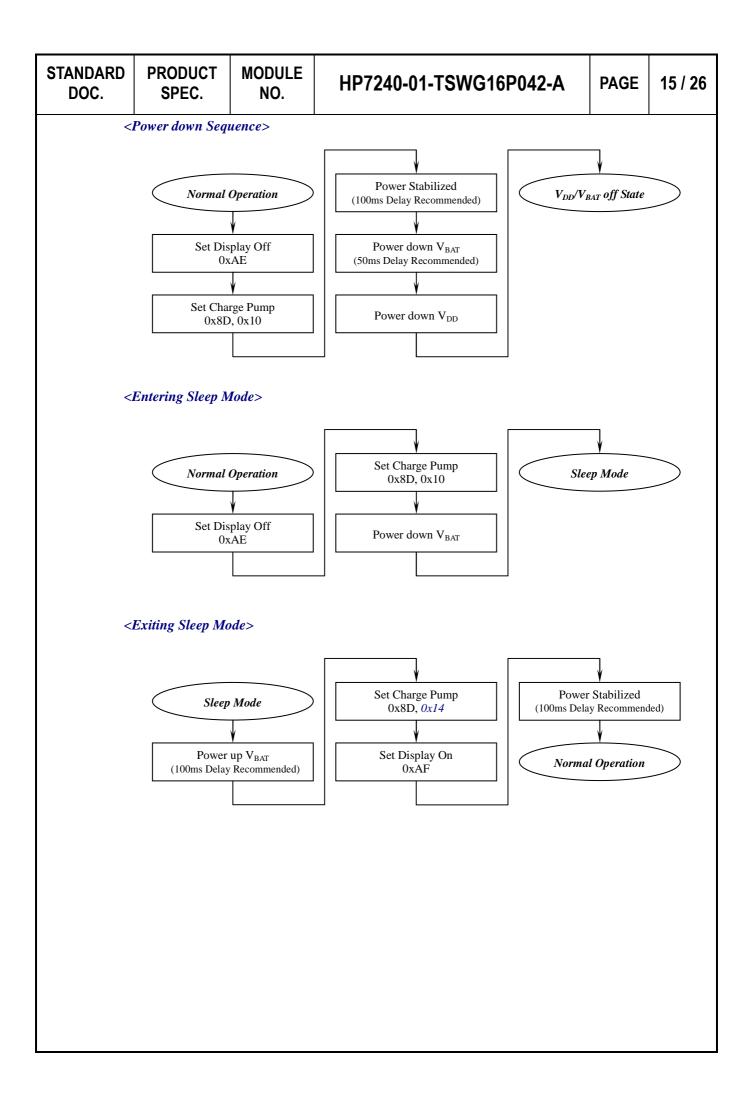
- - 1) Since an ESD protection circuit is connected between V_{DD} and V_{CC} inside the driver IC, V_{CC} becomes lower than V_{DD} whenever V_{DD} is ON and V_{CC} is OFF.
 - 2) V_{CC} / V_{BAT} should be kept float (disable) when it is OFF.
 - 3) Power Pins (V_{DD}, V_{CC}, V_{BAT}) can never be pulled to ground under any circumstance.
 - 4) V_{DD} should not be power down before V_{CC} / V_{BAT} power down.

1**0-3 Reset Circuit**

When RES# input is low, the chip is initialized with the following status:

- 1. Display is OFF
- 2. 128×64 Display Mode
- 3. Normal segment and display data column and row address mapping (SEG0 mapped to column address 00h and COM0 mapped to row address 00h)
- 4. Shift register data clear in serial interface
- 5. Display start line is set at display RAM address 0
- 6. Column address counter is set at 0
- 7. Normal scan direction of the COM outputs
- 8. Contrast control register is set at 7Fh
- 9. Normal display mode (Equivalent to A4h command)





STANDARD DOC.	PRODUCT SPEC.MODULE NO.HP7240-01-TSWG16P042-APAGE						
void Init_Lc	d(void)						
{							
RST=1;	1ms(100);						
RST=0;							
	1ms(100);						
RST=1;							
Delay_	1ms(100);						
Write_C	Command(0xAE);//s	set display displa	y ON/OFF,AFH/AEH				
Write_C	Command(0x40);//s	et display start lir	ne:COM0				
_	Command(0x81);//s Command(0x2F);	et contrast contro	bl				
Write (Command(0x20);//s	et memory addre	essing mode				
	Command(0x02);//p	•	-				
Write_C	Command(0xA0);//s	et segment re-m	ар				
Write_C	Command(0xA4);//e	entire display on:	A4H:OFF/A5H:ON				
Write_C	Command(0xA6);//s	et normal/inverse	e display: A6H:normal/A7H:inverse				
	Command(0xA8);//s Command(0x27);//1	•					
	Command(0xC0);//s	-	can direction				
	Command(0xD3);//s	set display offse	et				
Write_C	Command(0x00);//						
	Command(0xD5);//s Command(0x80);//1		k divide ratio/oscillator frequency				
Write_C	Command(0xD9);//s	et pre-charge pe	riod				
	Command(0x22);//						
	Command(0xDA);//s Command(0x12);//	set com pins hard	dware configuration				
	Command(0xAD);//s Command(0x30);//	set Internal IREF					

STANDARD DOC.	PRODUCT SPEC.	MODULE NO.	HP7240-01-TSWG16P042-A	PAGE	17 / 26					
	Command(0xDB);//s		ect level		I					
Write_C	Write_Command(0x20);//0.77*VCC									
Write_C	Command(0x8D);//c	charge pump sett	ing							
	Command(0x14);//e									
Write_C	Command(0xAF);//s	set display displa	y ON/OFF,AEH/AFH							
1										
ر void Write_0	Command (Uchar	Command)								
{	·	,								
int i;										
CS=0; A0=0;										
A0–0, for(i=0;i	<8:i++)									
{										
SCL										
	ommand&0x80)==())								
Si else	DA=0;									
	DA=1;									
SCL										
Com	mand=Command<	<1;								
} CS=1;										
}										
void Write_[Data (Uchar Data)									
{										
int i;										
CS=0; A0=1;										
for(i=0;i	i<8;i++)									
{										
SCL										
	ata&0x80)==0) DA=0;									
else	577 0,									
SI	DA=1;									
SCL										
Data ເ	=Data<<1;									
} CS=1;										
}										

STANDARD	
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11. RELIABILITY

ITEM	CONDITIONS	CRITERION	
OPERATING	HIGH TEMPERTURE +70°C 240HRS	NO DEFECT IN DISPLAYING AND	
TEMPERATURE	LOW TEMPERTURE -40°C 240HRS	OPERATIONAL FUNCTION	
STORAGE	HIGH TEMPERTURE +85°C 240HRS	NO DEFECT IN DISPLAYING AND	
TEMPERATURE	LOW TEMPERTURE - 40°C 240HRS	OPERATIONAL FUNCTION	
HUMIDITY	60℃ 90%RH 120HRS	NO DEFECT IN DISPLAYING AND	
		OPERATIONAL FUNCTION	
	Operating Time: thirty minutes exposure for		
VIBRATION	each direction (X,Y,Z)	NO DEFECT IN DISPLAYING AND	
VIDRATION	• Sweep Frequency: 10 \sim 55Hz (1 min)	OPERATIONAL FUNCTION	
	Amplitude: 1.5mm		
THERMAL	40° (60mine) \leftarrow > (85° (60mine) 24 evelop	NO DEFECT IN DISPLAYING AND	
SHOCK	-40° C (60mins) $\leftarrow \rightarrow +85^{\circ}$ C (60mins), 24 cycles	OPERATIONAL FUNCTION	

*NOTE: TEST CONDITION

(1)TEMPERATURE AND HUMIDITY: IF NO SPECIFICATION, TEMP. SET AT $25\pm2^\circ\!\mathrm{C}$, HUMIDITY SET AT $60\pm5\%\text{RH}$

(2) OPERATING STATE: SAMPLES SUBJECT TO THE TESTS SHALL BE IN " OPERATING" CONDITION

12. Outgoing Quality Control Specifications

12.1 Environment Required

Customer's test & measurement are required to be conducted under the following conditions:

Temperature:	$23 \pm 5^{\circ}C$
Humidity:	$55\pm15\%$ RH
Fluorescent Lamp:	30W
Distance between the Panel & Lamp:	≥ 50cm
Distance between the Panel & Eyes of the Inspector:	≥ 30cm
Finger glove (or finger cover) must be worn by the inspector.	
Inspection table or jig must be anti-electrostatic.	

12.2 Sampling Plan

Level II, Normal Inspection, Single Sampling, MIL-STD-105E

12.3 Criteria & Acceptable Quality Level

Partition	AQL	Definition
Major	0.65	Defects in Pattern Check (Display On)
Minor	1.0	Defects in Cosmetic Check (Display Off)

12.3.1 Cosmetic Check (Display Off) in Non-Active Area

Check Item	Classification	Criteria
Panel General Chipping	Minor	X > 6 mm (Along with Edge) Y > 1 mm (Perpendicular to edge)

ANDARD DOC.	PRODUCT SPEC.	MODULE NO.	HP7240-01	I-TSWG16P042-A	PAGE	20 / 2	
12.3.1	1 Cosmetic Check (Display Off) in Non-Active Area (Continued)						
	Check	ltem	Classification Criteria				
	Panel C	Prack	Minor	Any crack is not allo	wable.		
	Copper Ex (Even Pin	-	Minor	Not Allowable by Naked Eye Inspection			
	Film or Trace Damage		Minor	·ð·			
			Acceptable				
numin I i i i i i i i i i i i i i i i i i i i			Minor				
	Ink Marking on Bac (Exclude c		Acceptable	Ignore for Any	1		

12.3.2 Cosmetic Check (Display Off) in Active Area

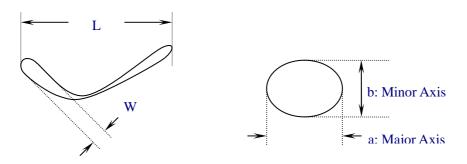
NO.

It is recommended to execute in clear room environment (class 10k) if actual in necessary.

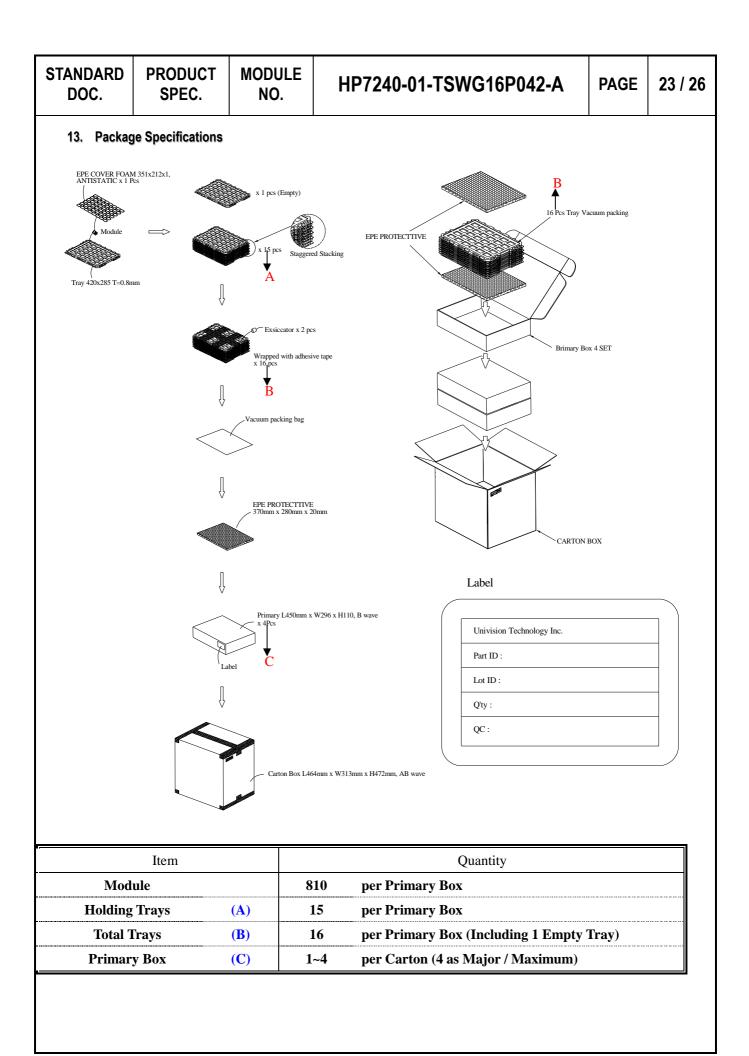
Check Item	Classification	Cr	iteria
Any Dirt & Scratch on Polarizer's Protective Film	Acceptable	Ignore for not Affect the Polarizer	
Scratches, Fiber, Line-Shape Defect (On Polarizer)	Minor	W ≤ 0.1 W > 0.1 L ≤ 2 L > 2	lgnore n ≤ 1 n = 0
Dirt, Black Spot, Foreign Material, (On Polarizer)	Minor	Φ ≤ 0.1 0.1 < Φ ≤ 0.25 0.25 < Φ	lgnore n ≤ 1 n = 0
Dent, Bubbles, White spot (Any Transparent Spot on Polarizer)	Minor	$\Phi \le 0.5$ \Rightarrow Ignore if no Influ $0.5 < \Phi$	ence on Display n = 0
Fingerprint, Flow Mark (On Polarizer)	Minor	Not A	llowable

* Protective film should not be tear off when cosmetic check.

** Definition of W & L & ϕ (Unit: mm): ϕ = (a + b) / 2



STANDARD DOC.	D PRODUCT MODULE SPEC. NO.		HP7240-01	1-TSWG16P042-A	PAGE	22 / 26
	Check	Item	Classification	Criteria		
	No Display Missing Line Pixel Short Darker Pixel Wrong Display Un-uniform		Major			
			Major			
			Major			
			Major		•	
			Major			
			Major			



14. Precautions When Using These OEL Display Modules

MODULE

NO.

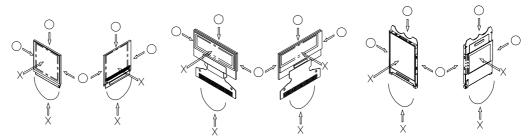
14.1 Handling Precautions

- 1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- If pressure is applied to the display surface or its neighborhood of the OEL display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- 4) The polarizer covering the surface of the OEL display module is soft and easily scratched. Please be careful when handling the OEL display module.
- 5) When the surface of the polarizer of the OEL display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
 - * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- Hold OEL display module very carefully when placing OEL display module into the system housing. Do not apply excessive stress or pressure to OEL display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- 7) Do not apply stress to the driver IC and the surrounding molded sections.
- 8) Do not disassemble nor modify the OEL display module.
- 9) Do not apply input signals while the logic power is off.
- 10) Pay sufficient attention to the working environments when handing OEL display modules to prevent occurrence of element breakage accidents by static electricity.
 - * Be sure to make human body grounding when handling OEL display modules.
 - * Be sure to ground tools to use or assembly such as soldering irons.
 - * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
 - * Protective film is being applied to the surface of the display panel of the OEL display module. Be careful since static electricity may be generated when exfoliating the protective film.
- 11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OEL display module has been stored for a long period of time, residue

STANDAF DOC.	RD PRODUCT SPEC.	MODULE NO.	HP7240-01-TSWG16P042-A	PAGE	25 / 26				
		•	may remain on the surface of the display panel after	removed of	the film. In				
12)			al by the method introduced in the above Section 5). OEL display module is being dewed or when it is pla	ced under h	niah humiditv				
,	If electric current is applied when the OEL display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.								
14.2	Storage Precaution	s							
1)	When storing OEL dis	play modules, pu	It them in static electricity preventive bags avoiding ex	posure to di	rect sun light				
	nor to lights of fluorescent lamps. and, also, avoiding high temperature and high humidity environment or low								
	temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Allvision technology Inc.)								
	• • • •		technology Inc.) e to the packages or bags nor let dewing occur with them.						
2)	If electric current is applied when water drops are adhering to the surface of the OEL display module, when the OEL display module is being dewed or when it is placed under high humidity environments, the electrodes may be								
	corroded and be careful about the above.								
14.3	Designing Precauti								
1)	The absolute maximu	ım ratings are tl	ne ratings which cannot be exceeded for OEL displa	ay module,	and if these				
	values are exceeded,								
2)		To prevent occurrence of malfunctioning by noise, pay attention to satisfy the V_{IL} and V_{IH} specifications and, at the							
3)		•	le as short as possible. current preventive unit (fuses, etc.) to the power circu	uit (Vpp) (Recommend				
5)	value: 0.5A)			int (VDD). (Recommend				
4)	,	n to avoid occurre	ence of mutual noise interference with the neighboring	devices.					
5)	As for EMI, take necessary measures on the equipment side basically.								
6)	When fastening the OEL display module, fasten the external plastic housing section.								
7)	7) If power supply to the OEL display module is forcibly shut down by such errors as taking out the								
8)	the OEL display panel is in operation, we cannot guarantee the quality of this OEL display module. The electric potential to be connected to the rear face of the IC chip should be as follows: SSD1315								
,			·						
Conn		other potential that	an the above may lead to rupture of the IC.						
14.4	Precautions when disposing of the OEL display modules								
1)	Request the qualified companies to handle industrial wastes when disposing of the OEL display modules. Or, wher burning them, be sure to observe the environmental and hygienic laws and regulations.								
14.5	Other Precautions								
1)	When an OEL display	module is opera	ted for a long of time with fixed pattern may remain as	s an after im	age or slight				
	contrast deviation may	occur.							
	Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there								
0)	will be no problem in t	•			the fall such as				
2)		-	performance drops by static electricity rapture, etc., do Iling the OEL display modules.	o not touch	the following				
	* Pins and electrodes		ang the OLL display modules.						
	* Pattern layouts suc								

- * Pattern layouts such as the FPC
- 3) With this OEL display module, the OEL driver is being exposed. Generally speaking, semiconductor elements

STANDAR DOC.		DDUCT Pec.	MODULE NO.	HP7240-01-TSWG16P042-A	PAGE	26 / 26					
change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OEL driver is exposed to light, malfunctioning may occur. * Design the product and installation method so that the OEL driver may be shielded from light in actual usage.											
	* Design the product and installation method so that the OEL driver may be shielded from light during the inspection processes.										
4)	Although this OEL display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.										
5)	We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.										
Warranty:											
The warranty period shall last twelve (12) months from the date of delivery. Buyer shall be completed to assemble all the processes within the effective twelve (12) months. Allvision technology Inc. shall be liable for replacing any products which contain defective material or process which do not conform to the product specification, applicable drawings and specifications during the warranty period. All products must be preserved, handled and appearance to permit efficient handling during warranty period. The warranty coverage would be exclusive while the returned goods are out of the terms above.											
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